

REMARKS/ARGUMENTS

Claim 1 has been amended. Claims 2-11 remain in the application.

The limitation, “means for simultaneously applying a polishing and dressing pressure to said head assemblies” as previously amended in Claim 1, has been removed. No new matter has been added.

Briefly, applicants wish to point out the major features of their claimed invention which is a novel apparatus for polishing substrates and, at the same time, conditioning the surface of the polishing pad. The instantaneousness of substrate polishing and pad conditioning provides the CMP operation a synergy for uniform polishing of larger diameter substrates.

A plurality of coaxial polishing-dressing head devices, holding large substrates to be polished are rotated along its central axis while pressing the substrates within an outer radial segment of the rotating polishing pad. A pad-dressing ring is mounted coaxially encircling each of the substrate supporting heads. Pad dressing raises the nap of the polishing pad preventing a hard glazed surface to form. The applied compression on the substrate supporting heads pushes the substrate and the coaxially mounted dressing ring against the upper surface of the polishing pad, hence, polishing a substrate while, at the same time, dressing the polishing pad.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned.

**"Version with markings to show changes made."**

Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

Respectfully submitted,

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**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

**In the Claims:**

Please amend claim 1 as follows:

1. (THRICE AMENDED) A polishing-dressing head for a polishing apparatus comprising:  
a plurality of substrate head assemblies each having a lower nesting surface opposed to an upper surface of a polishing pad, said lower nesting surface releasably holds a substrate to be polished, said substrate head assemblies, each rotating along a central axis thereof and polishing the substrates on an outer radial portion of said rotating polishing pad;  
annular dressing rings for dressing said polishing pad, said dressing rings are positioned coaxially encircling each nested substrate, said annular dressing rings are removably attached to said lower surface of said substrate head assemblies[, and  
means for simultaneously applying a polishing and dressing pressure to said head assemblies, whereby the substrate head assemblies are urged against the upper surface of the rotating polishing pad].